

Sir:

011504

Transmitted herewith for filing is the Patent Application of:

Inventor: SHIH-YEN TSAI, PO-HSIUNG LEU, CHIA-MING YANG, TSANG-YU LIU, YUH-DA FAN, CHEN-PENG FAN

For: SOLUTION FOR COPPER HILLOCK INDUCED BY THERMAL STRAIN WITH BUFFER ZONE FOR STRAIN

RELAXATION

Enclosed are:							
x	4 sheets of drawing(s) - formal.						
x	An assignment of the invention to Taiwan Semiconductor Manufacturing Co.						
	An associate power of attorney Applicant claims small entity status						
	Request & Certification under 35 USC 122(b)(2)(b)(i)						
The filing fee has been calculated as shown below:							
	(Col. 1) (Col. 2)		(Col. 2)	OTHER THAN A	OTHER THAN A SMALL ENTITY		
FOR:	A 11/2	NO. FILED	NO. EXTRA	RATE	FEE		
BASIC FEE		><	\geq		\$ 770.		
TOTAL	CLAIMS	20 -20=	0	x 18 =	\$ 0.	•	
INDEP	CLAIMS	3 -3=	0	x 86 =	\$ 0,		
				SUB TOTAL	\$ 770.		
				ASSIGNMENT	\$40.		
				TOTAL	\$ 810,		
x	Please charge my Deposit Account No. 19-0033 in the amount of \$810. A duplicate copy of this sheet is enclosed.						
х	The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any						
	overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.						
	XA	X Any additional filing fees required under 37 CFR §1.16.					
	X Any patent application processing fees under 37 CFR §1.17.						
Respectfists submitted,							
	STEPHEND CKERMAN, REG. NO. 37,761						

EXPRESS MAIL CERTIFICATE

Express Mail No.EV385357641US

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/or Attorney requests the date of deposit as the Filing Date.

Date of deposit.

Signature / Date